

HAOPIN MICROELECTRONICS CO.,LTD.

Description

Passivated high commutation triacs in a plastic envelope intended for use in circuits where high static and dynamic dV/dt and high dI/dt can occur. These devices will commutate the full rated ms current at the maximum rated junction temperature without the aid of a snubber.

| Symbol | Simplified outline |
|---|---|
|  |  TO-220 |
| Pin | Description |
| 1 | Main terminal 1 (T1) |
| 2 | Main terminal 2 (T2) |
| 3 | gate (G) |
| TAB | isolated |

Applications:

- ◆ Motor control
- ◆ Industrial and domestic lighting
- ◆ Heating
- ◆ Static switching

Features

- ◆ Blocking voltage to 600 V
- ◆ On-state RMS current to 20 A

| SYMBOL | PARAMETER | Value | Unit |
|---------------------|--|-------|------|
| V_{DRM} | Repetitive peak off-state voltages | 600 | V |
| $I_T \text{ (RMS)}$ | RMS on-state current (full sine wave) | 20 | A |
| I_{TSM} | Non-repetitive peak on-state current (full cycle, $T_j \text{ initial} = 25^\circ\text{C}$) | 200 | A |

| SYMBOL | PARAMETER | CONDITIONS | MIN | TYP | MAX | UNIT |
|---------------|----------------------|------------|-----|-----|-----|------|
| $R_{th(j-c)}$ | Junction to case(AC) | | - | 2.1 | - | °C/W |
| $R_{th(j-a)}$ | Junction to ambient | | - | 60 | - | °C/W |



BTA20-600BW

Three quadrant triacs

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Limiting values in accordance with the Maximum system(IEC 134)

| SYMBOL | PARAMETER | CONDITIONS | | MAX | Value | UNIT | | |
|--------------|--|---|------------------------|------|-------|------------|--|--|
| V_{DRM} | Repetitive peak off-state Voltages | $T_j=125^\circ C$ | | - | 600 | V | | |
| $I_{T(RMS)}$ | RMS on-state current | 360° conduction angle $T_c=70^\circ C$ | | - | 20 | A | | |
| I_{TSM} | Non repetitive surge peak on-state current | full cycle, T_j initial= $25^\circ C$ | | - | 210 | A | | |
| | | | | - | 200 | A | | |
| I^2t | I^2t value | $T_p=10ms$ | | - | 200 | A^2s | | |
| DI/dt | Critical rate of rise of on-state current | Gate supply: $I_g=500mA$ $dI_g/dt=1A/us$ | Repetitive $F=50Hz$ | - | 20 | $A/\mu s$ | | |
| | | | Non repetitive | - | 100 | | | |
| I_{DRM} | V_{DRM} rated | $T_j=25^\circ C$ | | 0.01 | - | mA | | |
| I_{RRM} | V_{RRM} rated | $T_j=125^\circ C$ | | 3 | - | mA | | |
| T_I | Maximum lead soldering temperature during 10s at 4.5mm form case | | | - | 260 | $^\circ C$ | | |
| T_{sg} | Storage and operating junction temperature range | | | -40 | 150 | $^\circ C$ | | |
| T_j | Storage and operating junction temperature range | | | -40 | 125 | $^\circ C$ | | |

$T_j=25^\circ C$ unless otherwise stated

| SYMBOL | PARAMETER | CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------------|------------------------------|-------------------|----------|-----|-----|-------------|
| Static characteristics | | | | | | |
| I_{GT} | | | | | | |
| V_{GT} | $V_D=12V(DC); R_L=33\Omega$ | $T_j=25^\circ C$ | I-II-III | 2 | - | 50 mA |
| | | | I-II-III | - | - | 1.5 V |
| I_L | $I_g=1.2 I_{GT}$ | $T_j=25^\circ C$ | I-III | - | 50 | - mA |
| | | | II | - | 90 | - |
| | | | I-II-III | - | - | - |
| I_H | $I_T=500mA$ Gate open | $T_j=25^\circ C$ | - | - | 75 | mA |
| V_{GD} | $V_D=V_{DRM} R_L=3.3K\Omega$ | $T_j=125^\circ C$ | I-II-III | 0.2 | - | - V |
| dV/dt | $V_D=67\%V_{DRM}$ gate open; | $T_j=125^\circ C$ | | 500 | 750 | - $V/\mu s$ |
| $(dv/dt)c$ | Without snubber | $T_j=125^\circ C$ | | 18 | 36 | - A/ms |

Dynamic Characteristics

| | | | | | | |
|-------------|--|------------------|----------|---|------|---------|
| $V_{TM}(2)$ | $I_{TM}=28A$ $tp=380\mu s$ | $T_j=25^\circ C$ | - | - | 1.70 | V |
| tgt | $V_D=V_{DRM}$ $I_g=500mA$ $dI_g/dt=3A/us$ | $T_j=25^\circ C$ | I-II-III | - | 2 | μs |

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Fig. 1: Maximum RMS power dissipation versus RMS on-state current ($F = 50\text{Hz}$). (Curves are cut off by $(dI/dt)_c$ limitation)

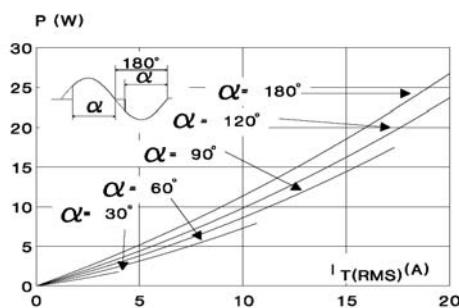


Fig. 2: Correlation between maximum RMS power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact (BTA).

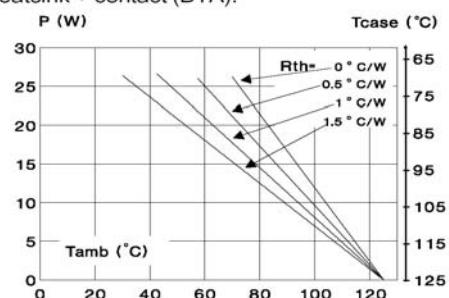


Fig. 3: Correlation between maximum RMS power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact (BTB).

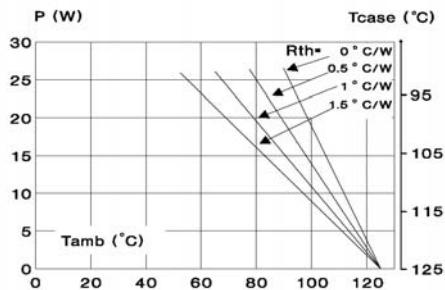


Fig. 4: RMS on-state current versus case temperature.

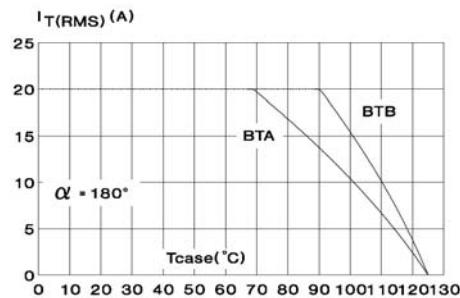


Fig. 5: Relative variation of thermal impedance versus pulse duration.

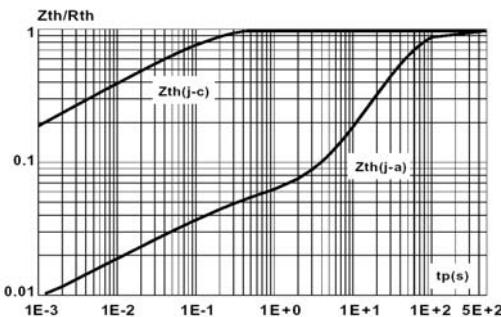
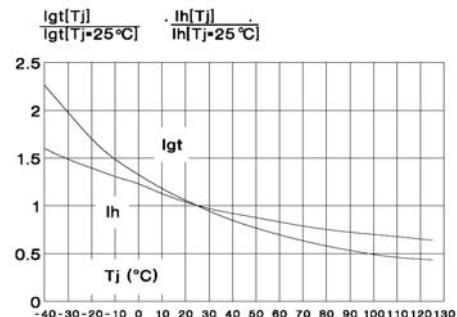


Fig. 6: Relative variation of gate trigger current and holding current versus junction temperature.



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Fig. 7: Non repetitive surge peak on-state current versus number of cycles.

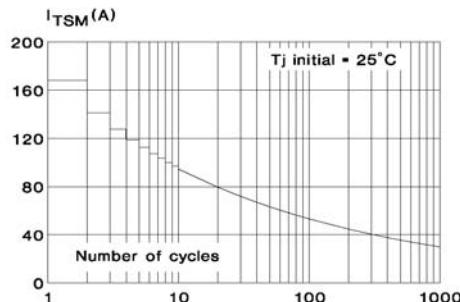


Fig. 8: Non repetitive surge peak on-state current for a sinusoidal pulse with width: $t \leq 10\text{ms}$, and corresponding value of I^2t .

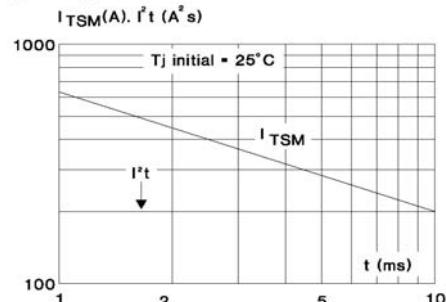
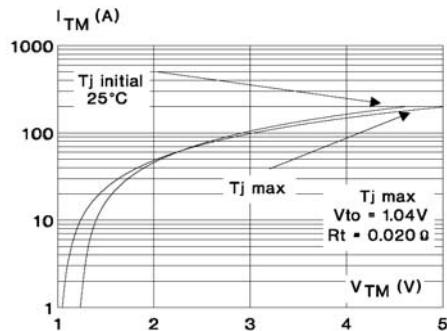
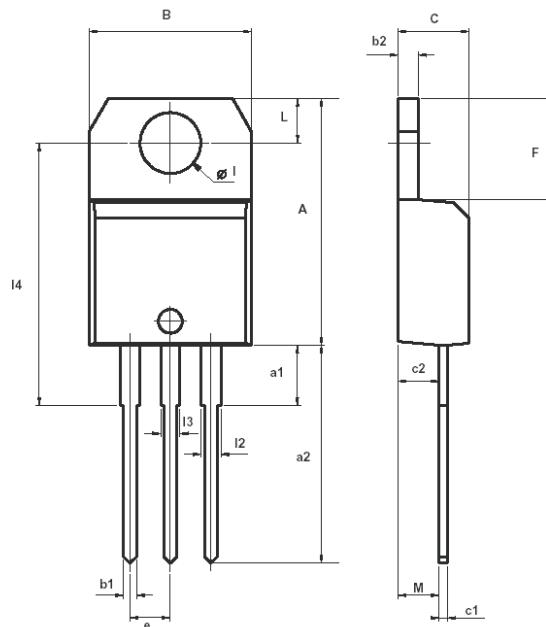


Fig. 9: On-state characteristics (maximum values).



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MECHANICAL DATA

Dimensions in mm
Net Mass: 2 g



| REF. | DIMENSIONS | | | | | |
|------|-------------|-------|-------|--------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 15.20 | | 15.90 | 0.598 | | 0.625 |
| a1 | | 3.75 | | | 0.147 | |
| a2 | 13.00 | | 14.00 | 0.511 | | 0.551 |
| B | 10.00 | | 10.40 | 0.393 | | 0.409 |
| b1 | 0.61 | | 0.88 | 0.024 | | 0.034 |
| b2 | 1.23 | | 1.32 | 0.048 | | 0.051 |
| C | 4.40 | | 4.60 | 0.173 | | 0.181 |
| c1 | 0.49 | | 0.70 | 0.019 | | 0.027 |
| c2 | 2.40 | | 2.72 | 0.094 | | 0.107 |
| e | 2.40 | | 2.70 | 0.094 | | 0.106 |
| F | 6.20 | | 6.60 | 0.244 | | 0.259 |
| I | 3.75 | | 3.85 | 0.147 | | 0.151 |
| I4 | 15.80 | 16.40 | 16.80 | 0.622 | 0.646 | 0.661 |
| L | 2.65 | | 2.95 | 0.104 | | 0.116 |
| I2 | 1.14 | | 1.70 | 0.044 | | 0.066 |
| I3 | 1.14 | | 1.70 | 0.044 | | 0.066 |
| M | | 2.60 | | | 0.102 | |